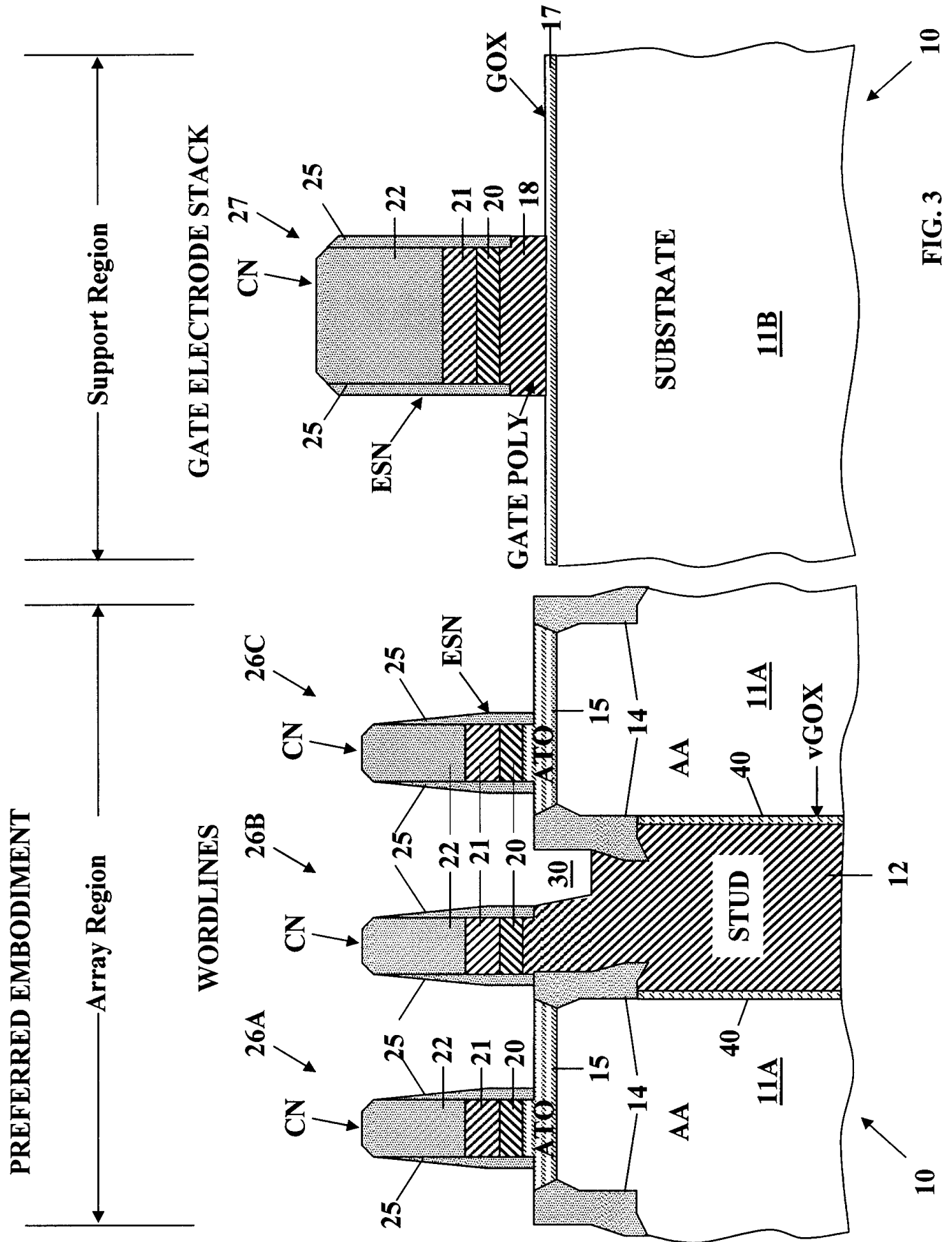


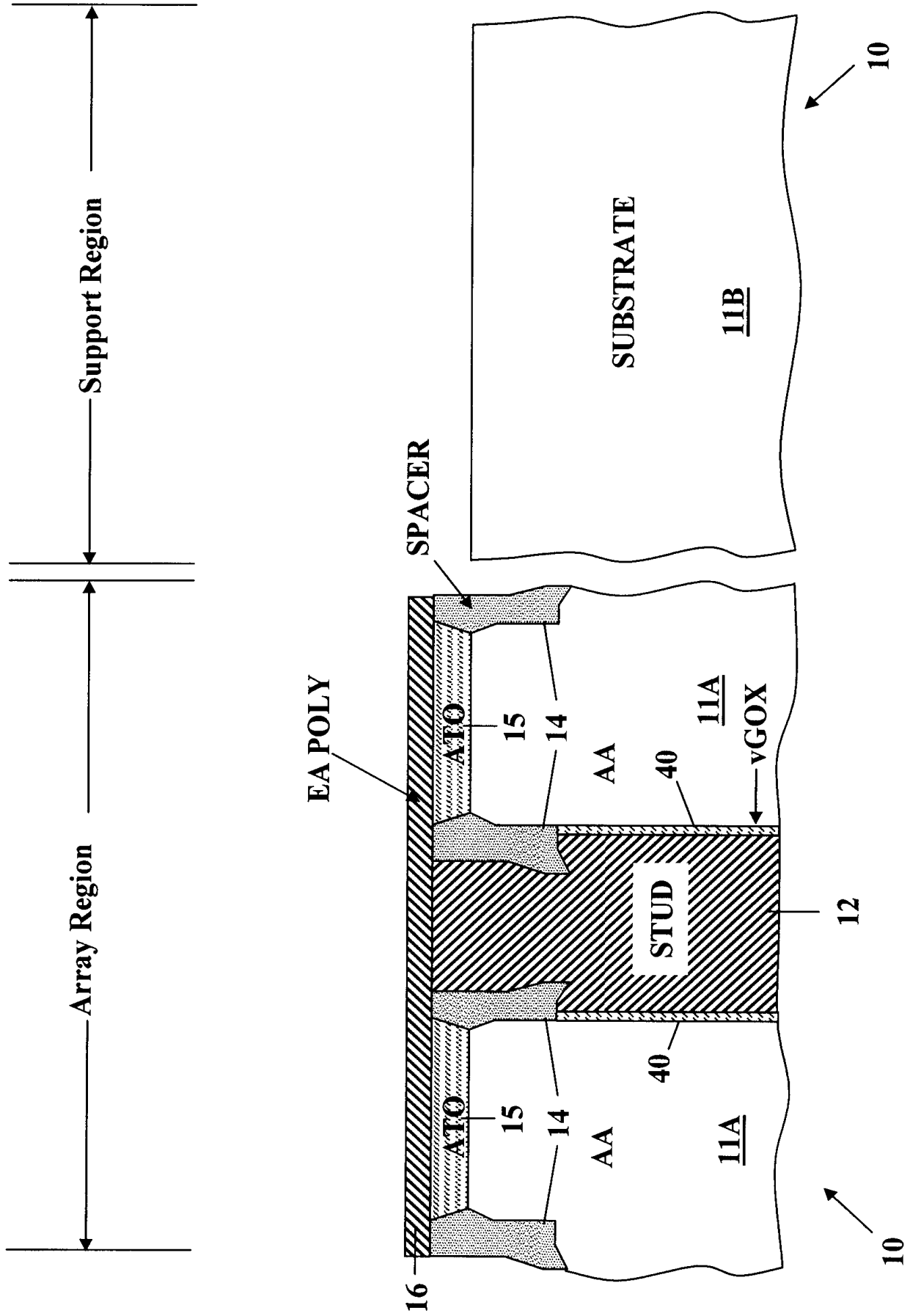




3/21



# 1. TOE (TOP OXIDE EARLY) PROCESS FOR ATO (ARRAY REGION TOP OXIDE)



• Post ES/EA process(prior art)

FIG. 4

2. GATE OXIDATION

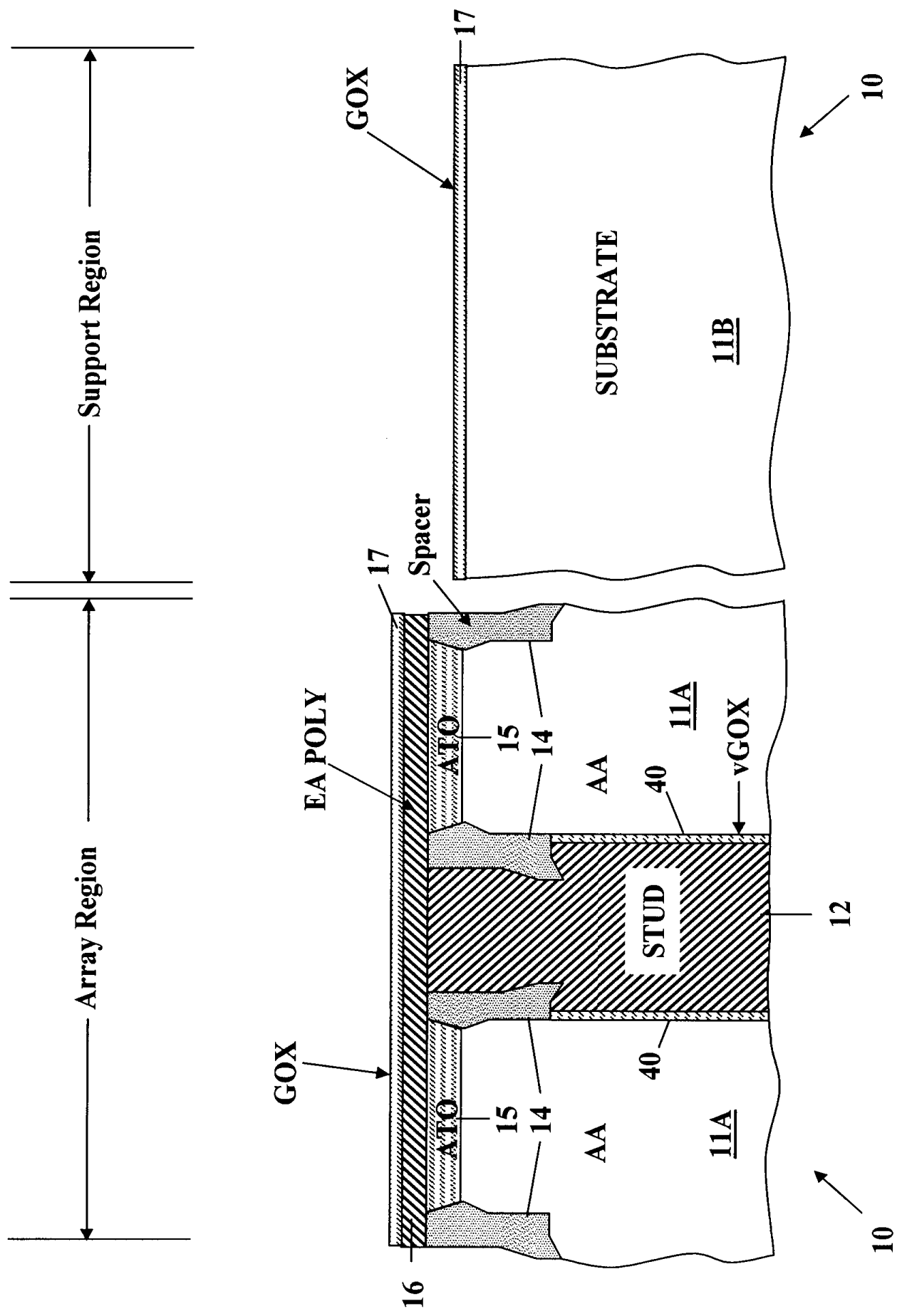


FIG. 5

### 3. THICK GATE POLYSILICON DEPOSITION

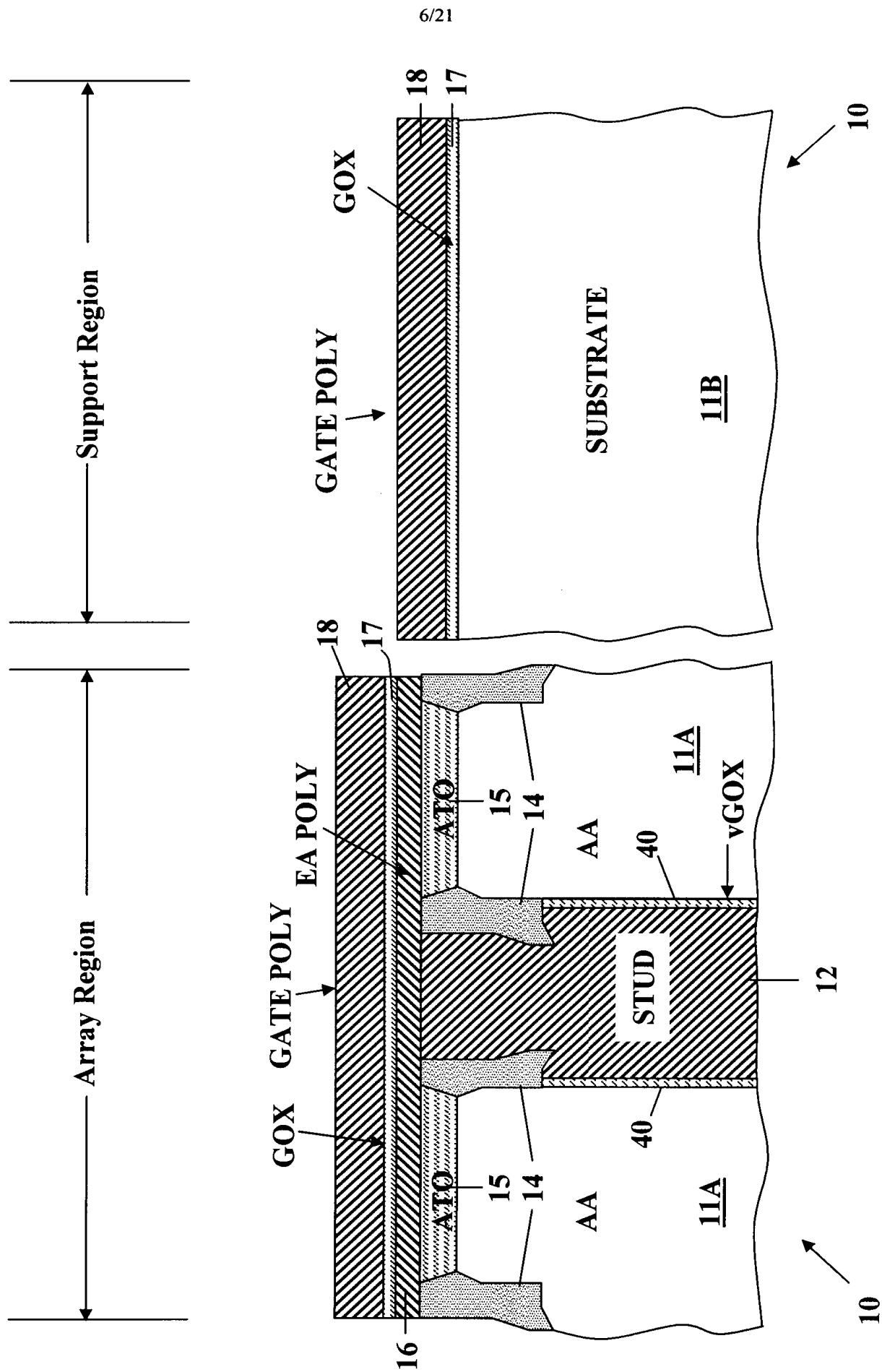


FIG. 6

7/21

# 4. BLOCKING MASK AT SUPPORT REGION

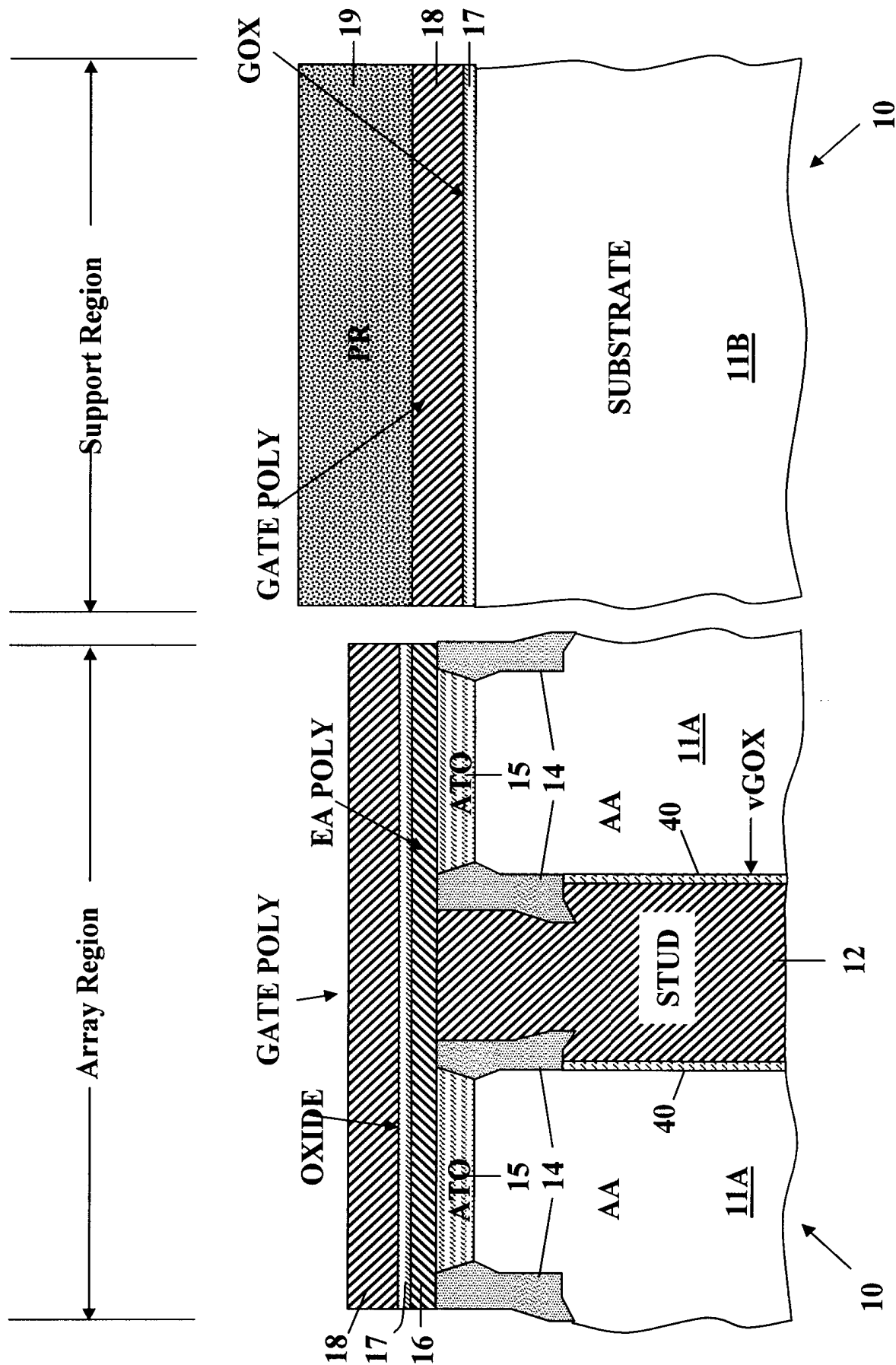


FIG. 7

# 5. POLYSILICON REMOVAL FROM ARRAY REGION

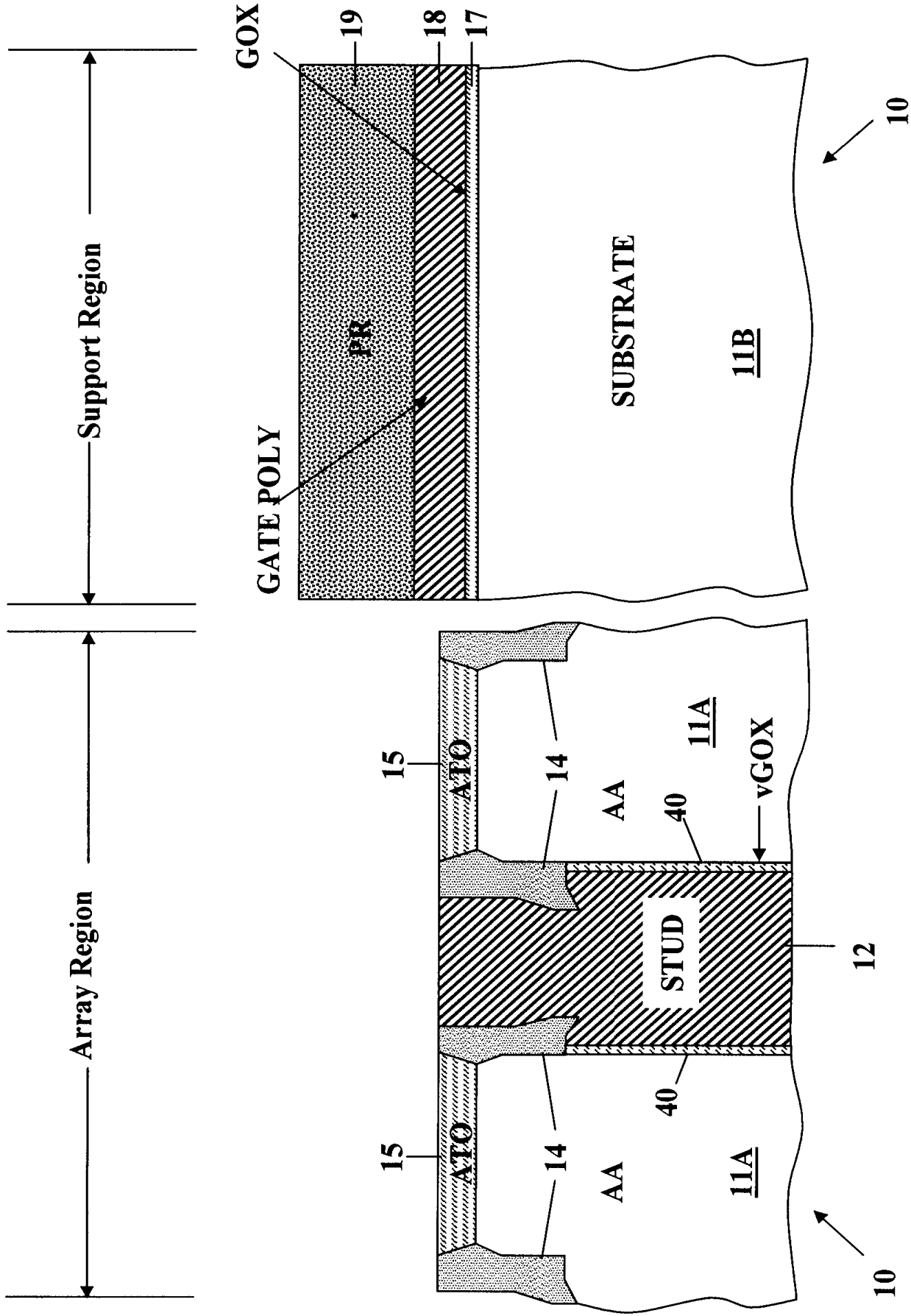


FIG. 8



9/21

# 6. PHOTORESIST STRIP

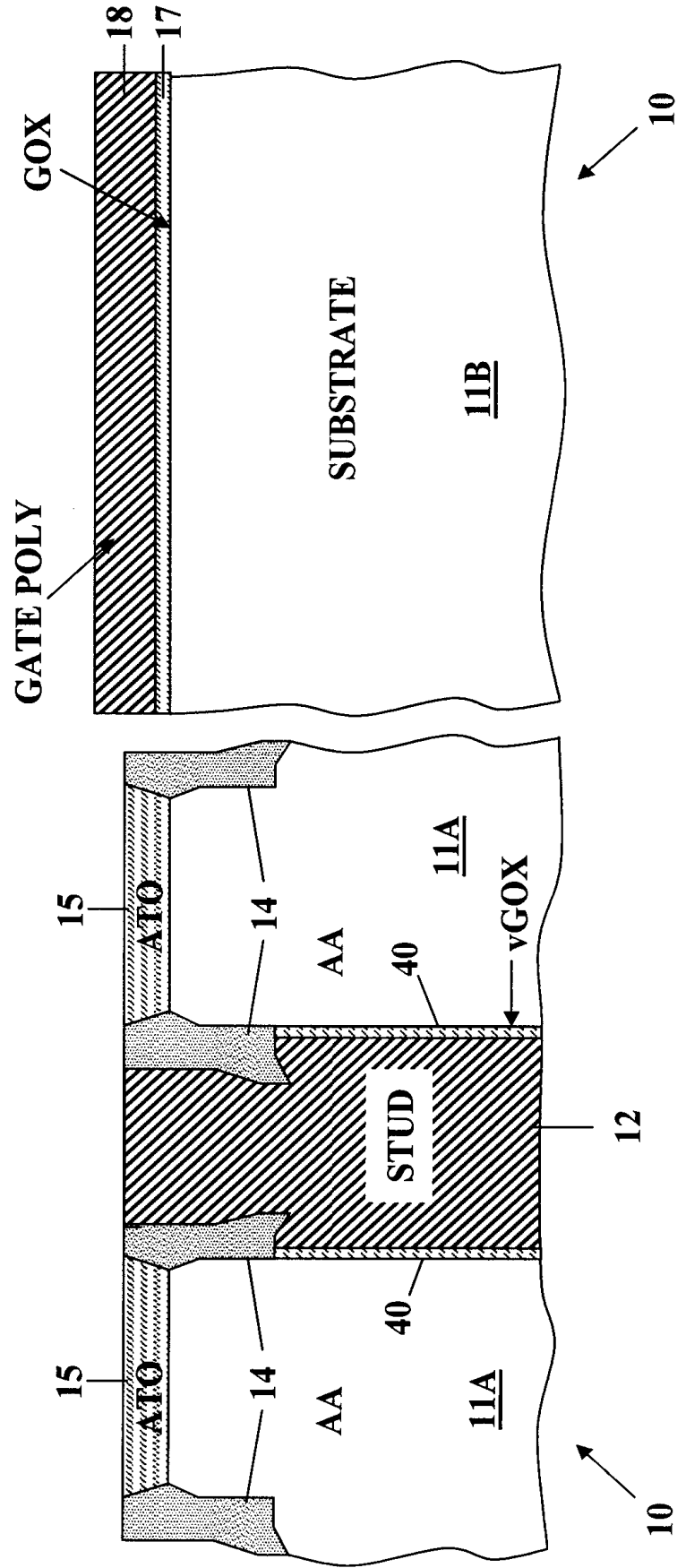
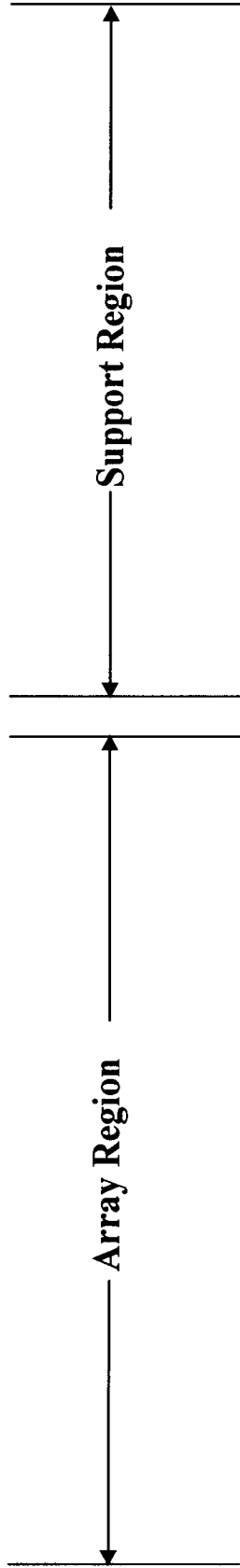
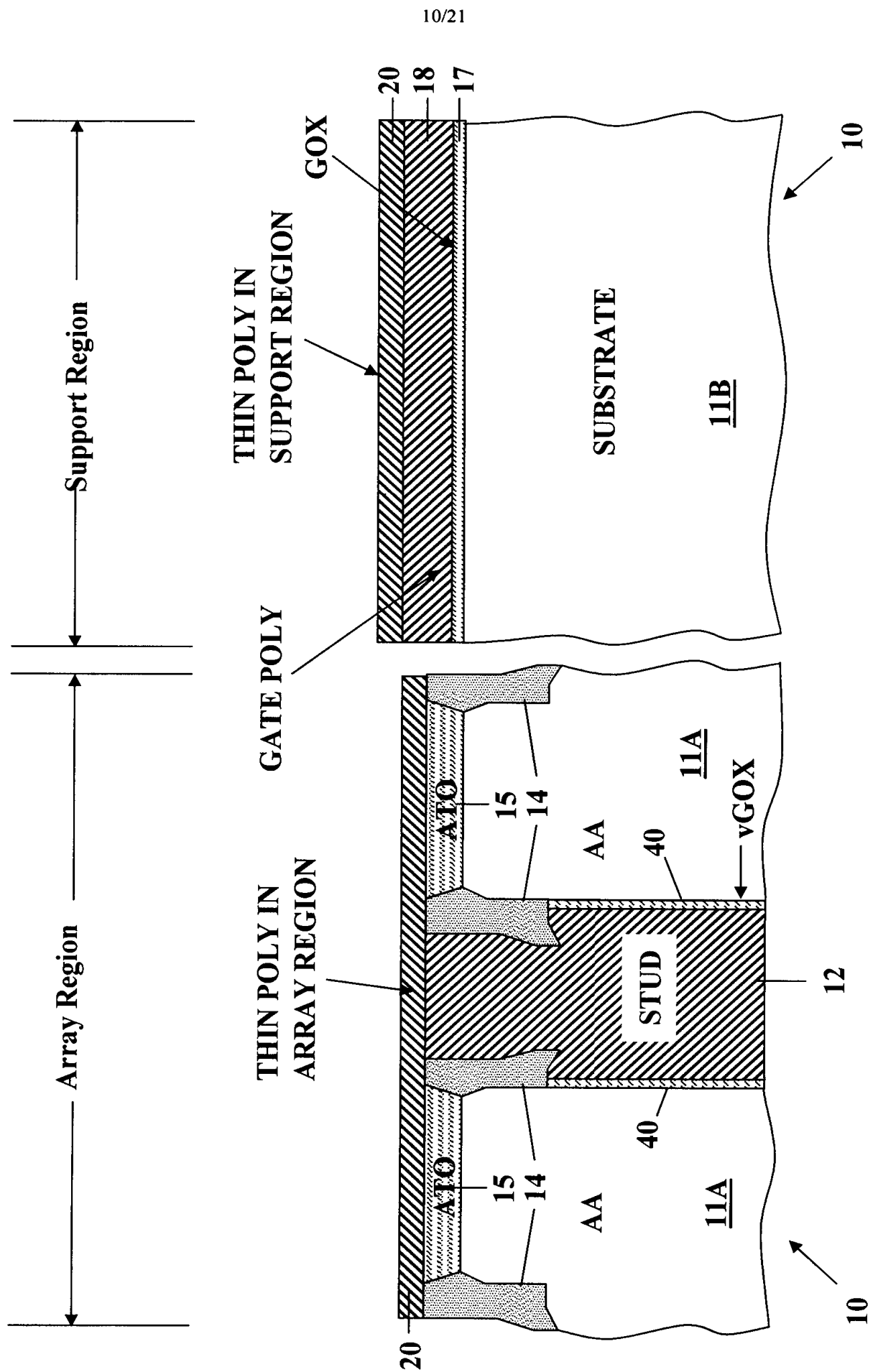


FIG. 9

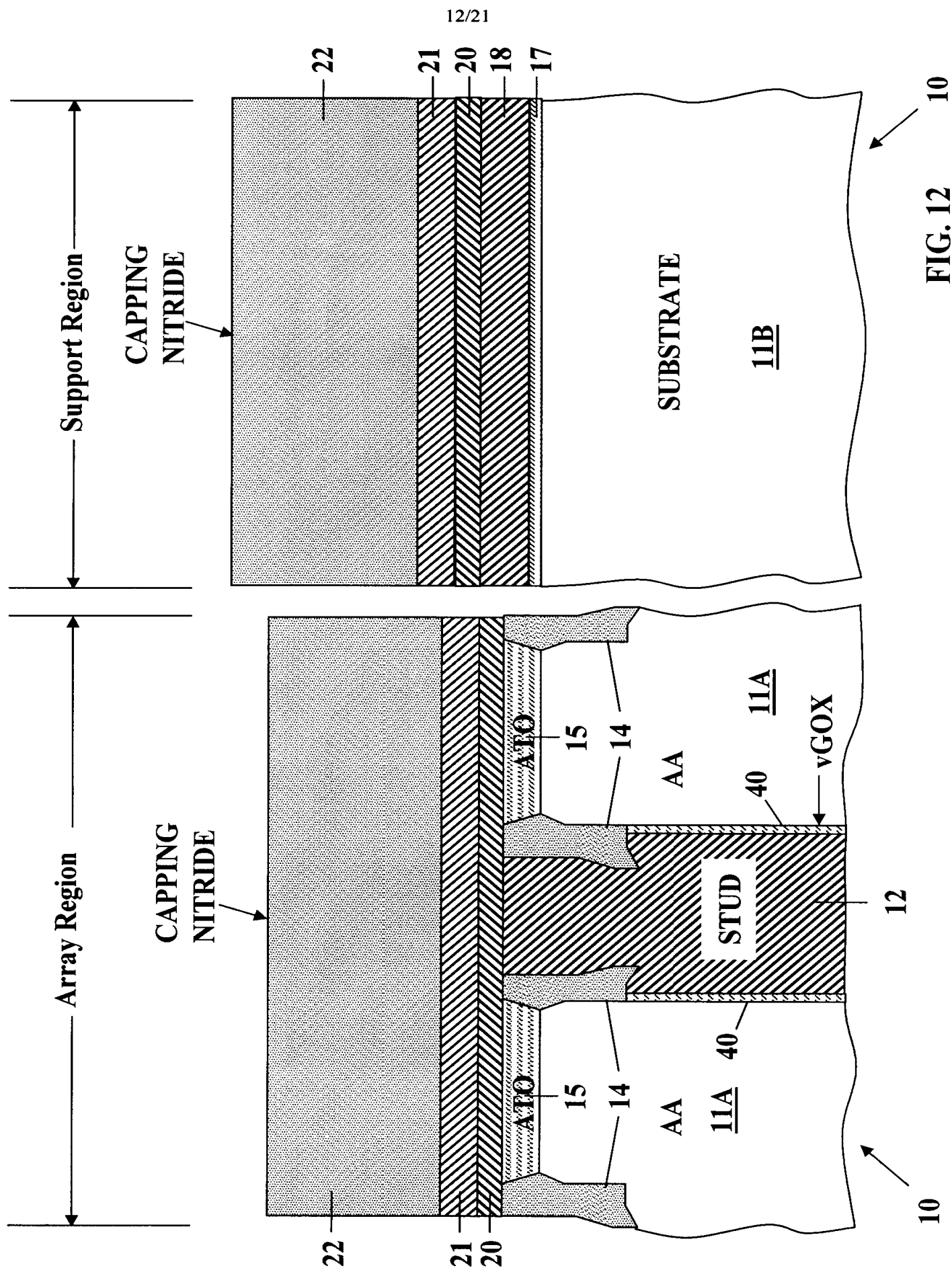
## 7. PRECLEANING AND THIN POLYSILICON DEPOSITION



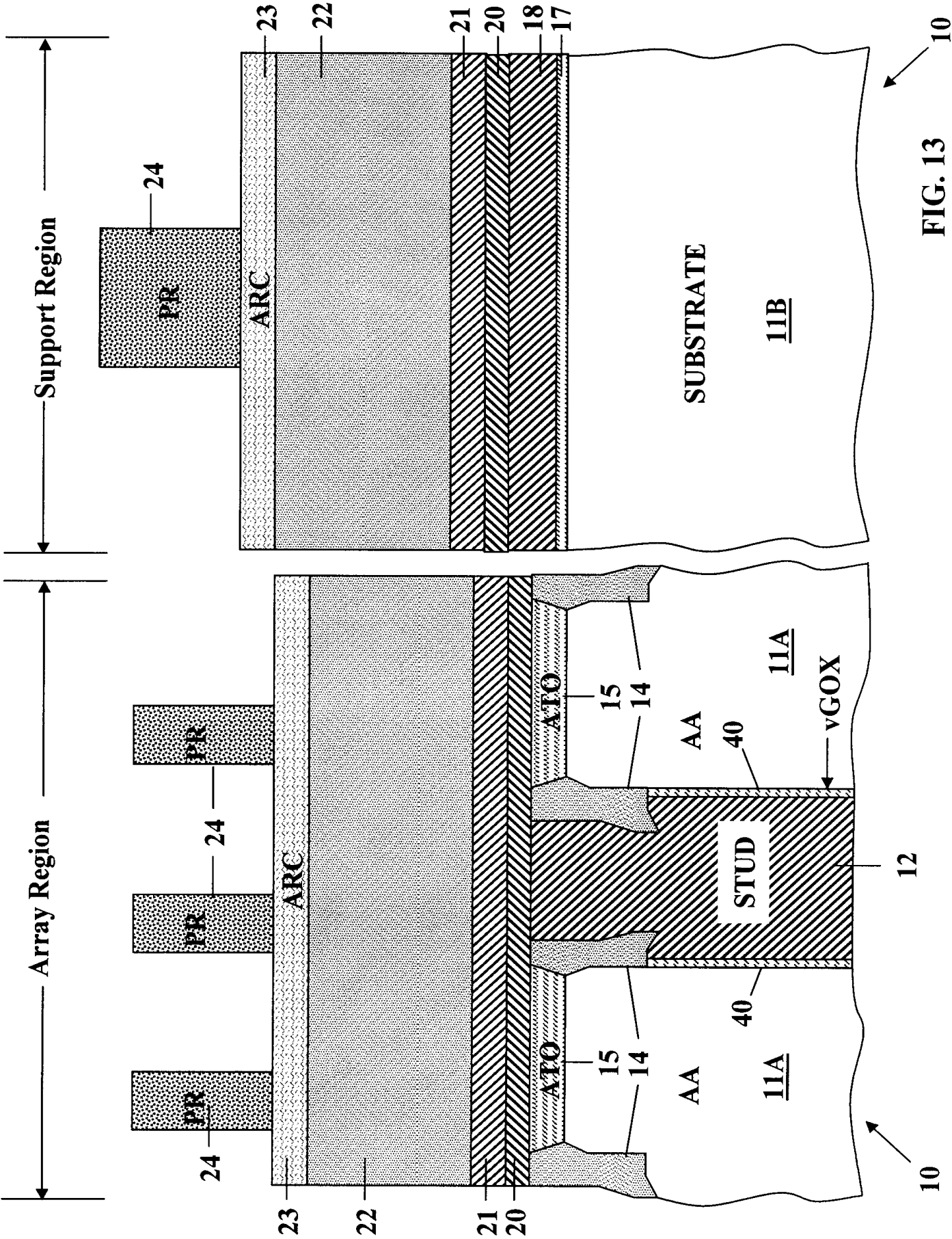
A diagram illustrating the regions of a 1D array. A horizontal line represents the array. A double-headed arrow below the line is labeled "Array Region". To the right of this, another double-headed arrow is labeled "Support Region".



# 9. CAPPING NITRIDE DEPOSITION



10. GATE PATTERNING





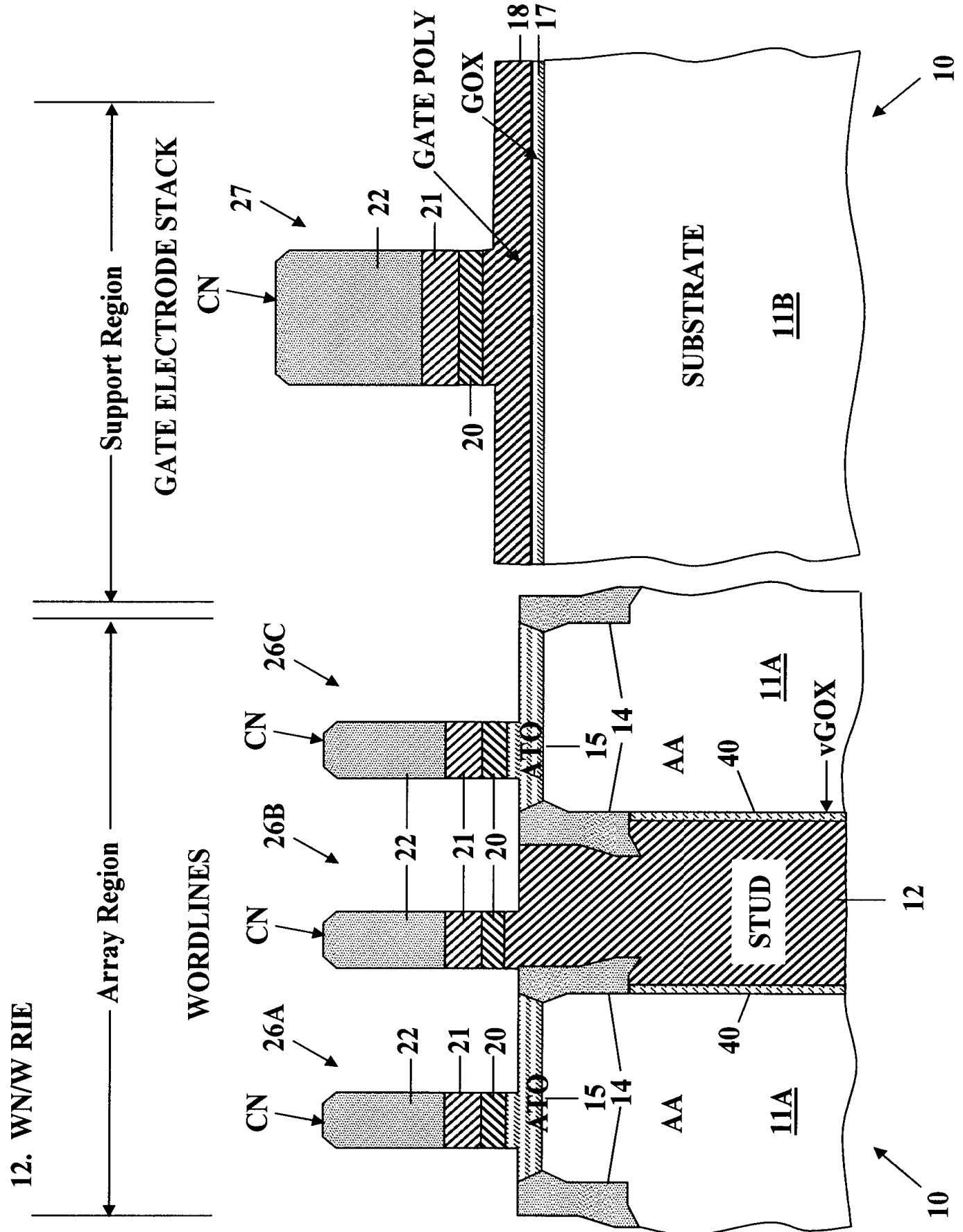


FIG. 15

16/21

13. ENCAPSULATING SPACER NITRIDE DEPOSITION

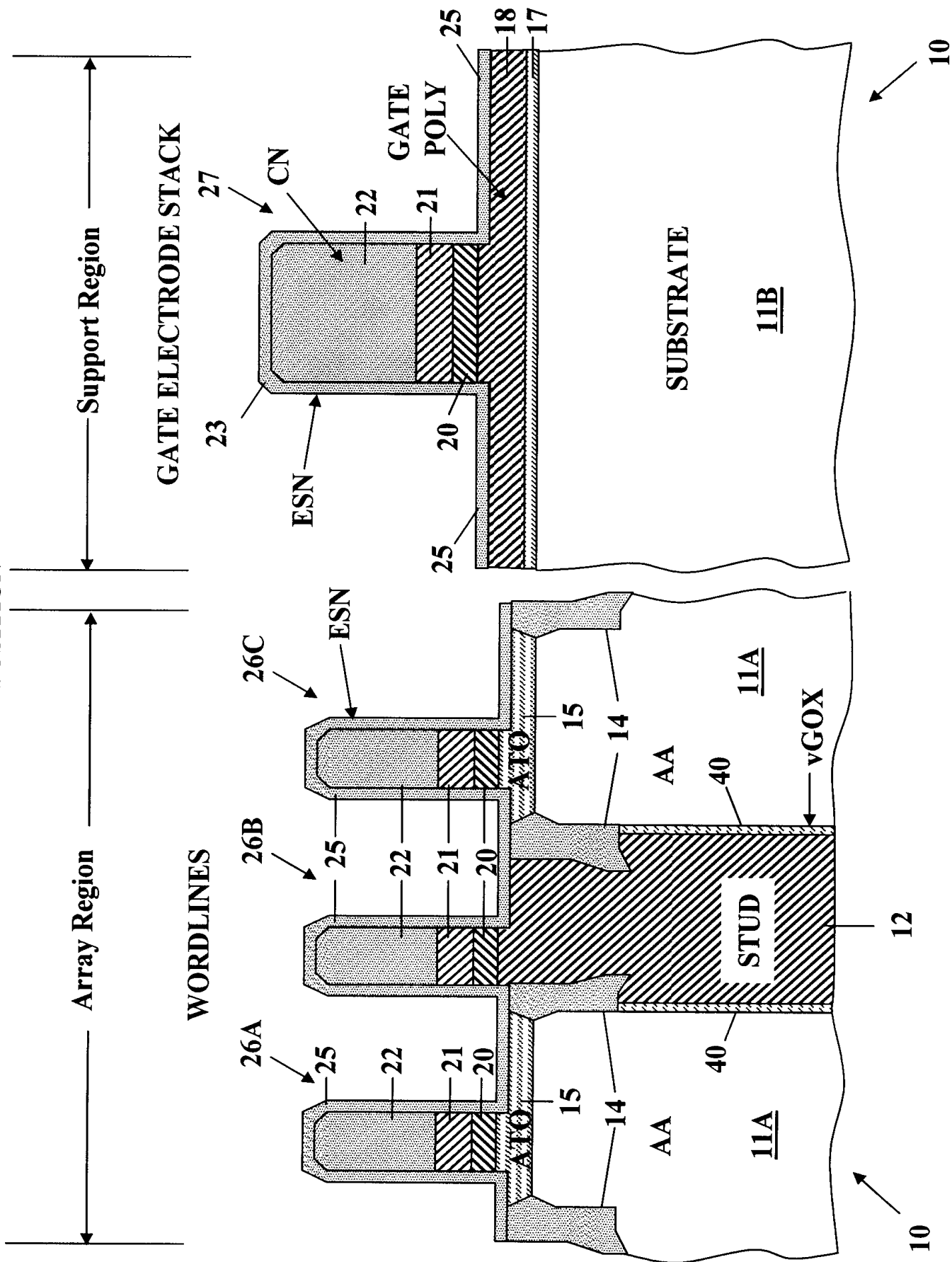


FIG. 16



17/21

## 14. ENCAPSULATING SPACER RIE

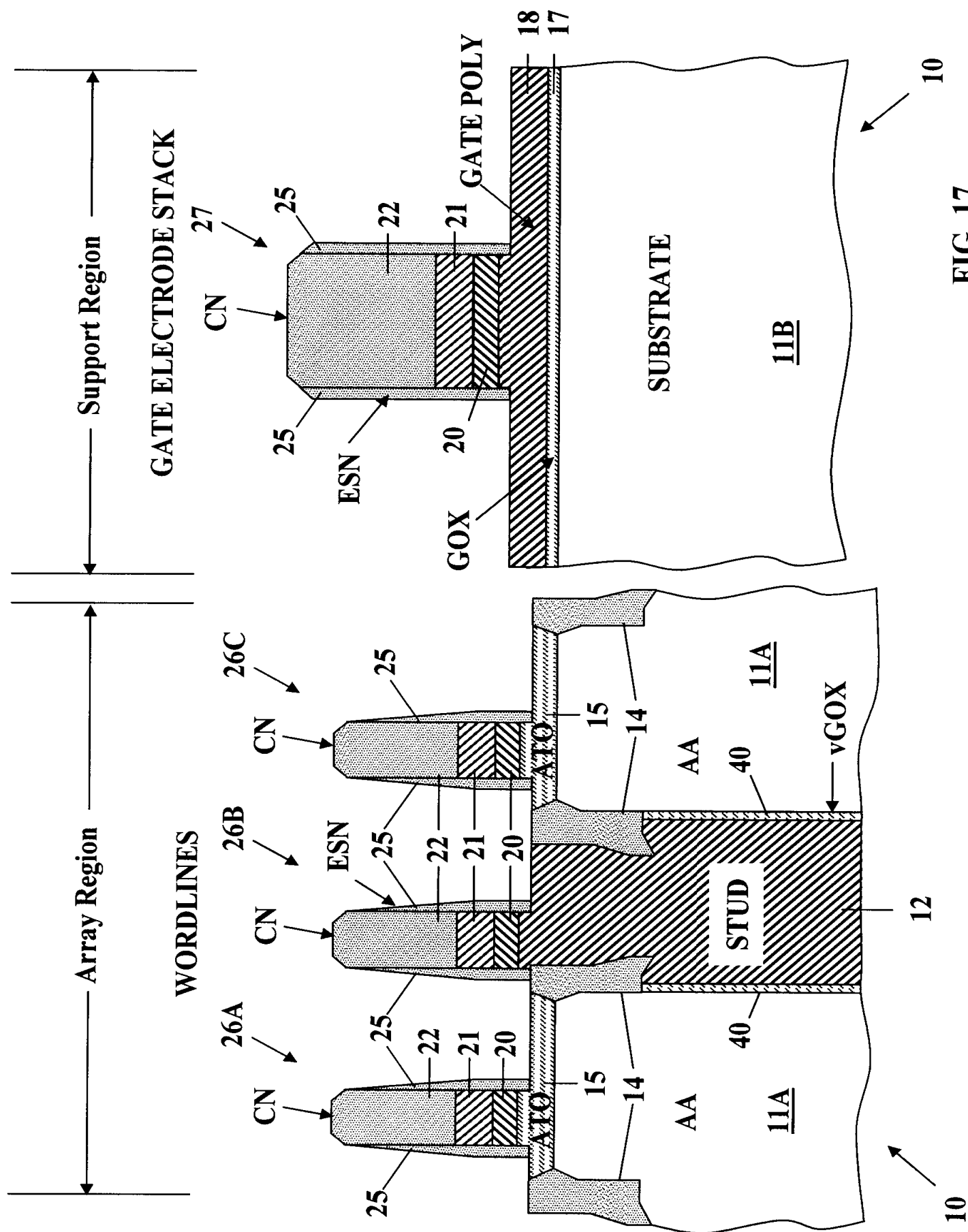
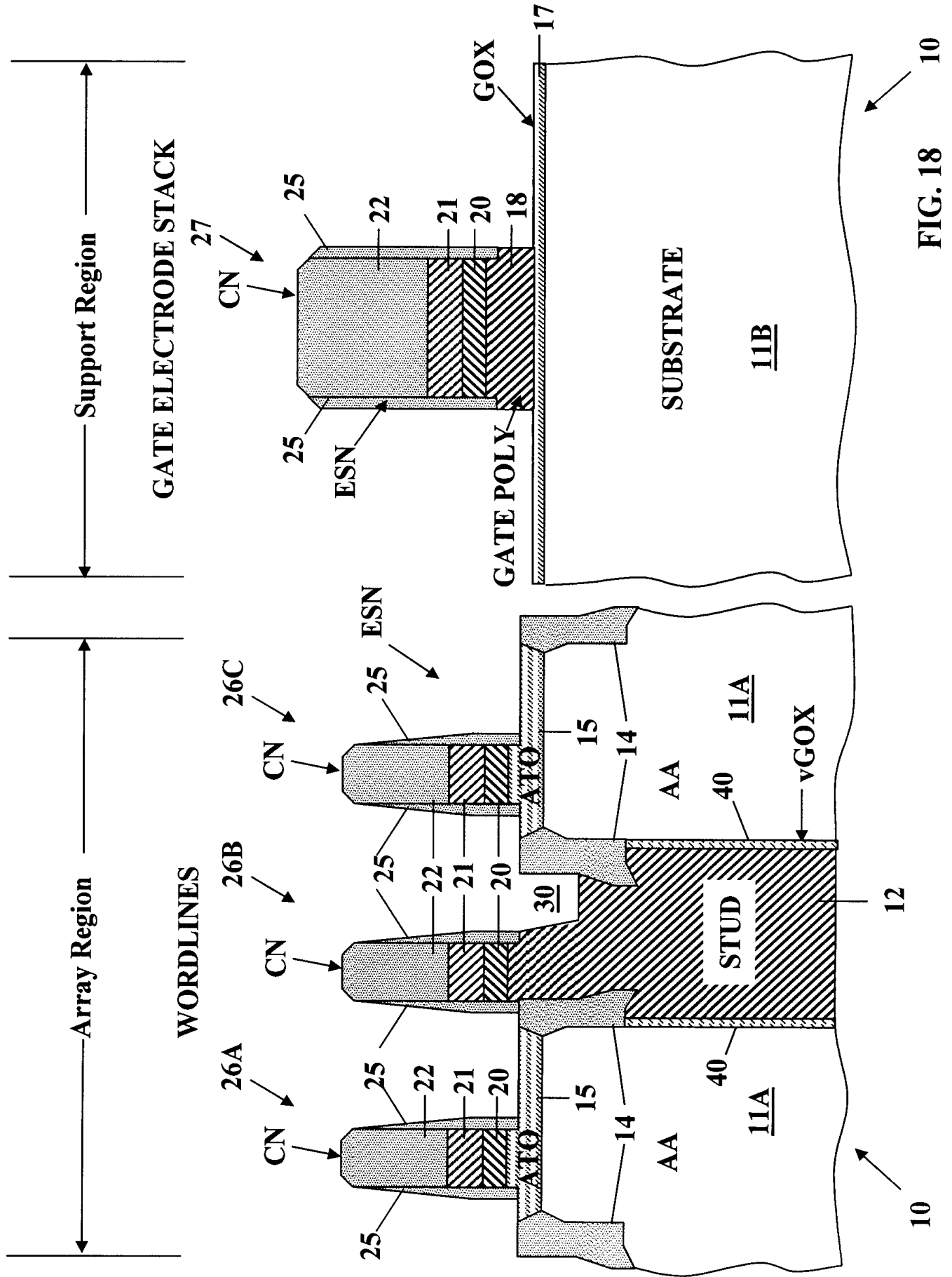


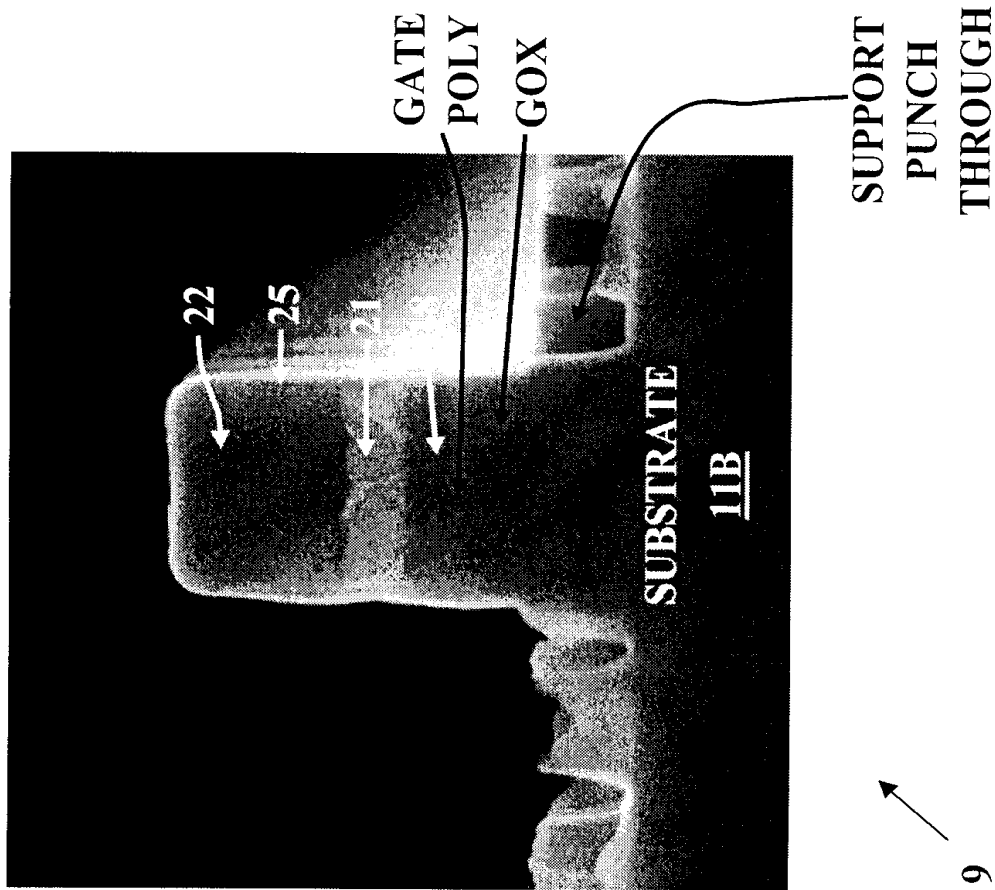
FIG. 17

18/21

## 15. GATE POLYSILICON RIE



SUPPORT PUNCH THROUGH



PRIOR ART

FIG. 19A

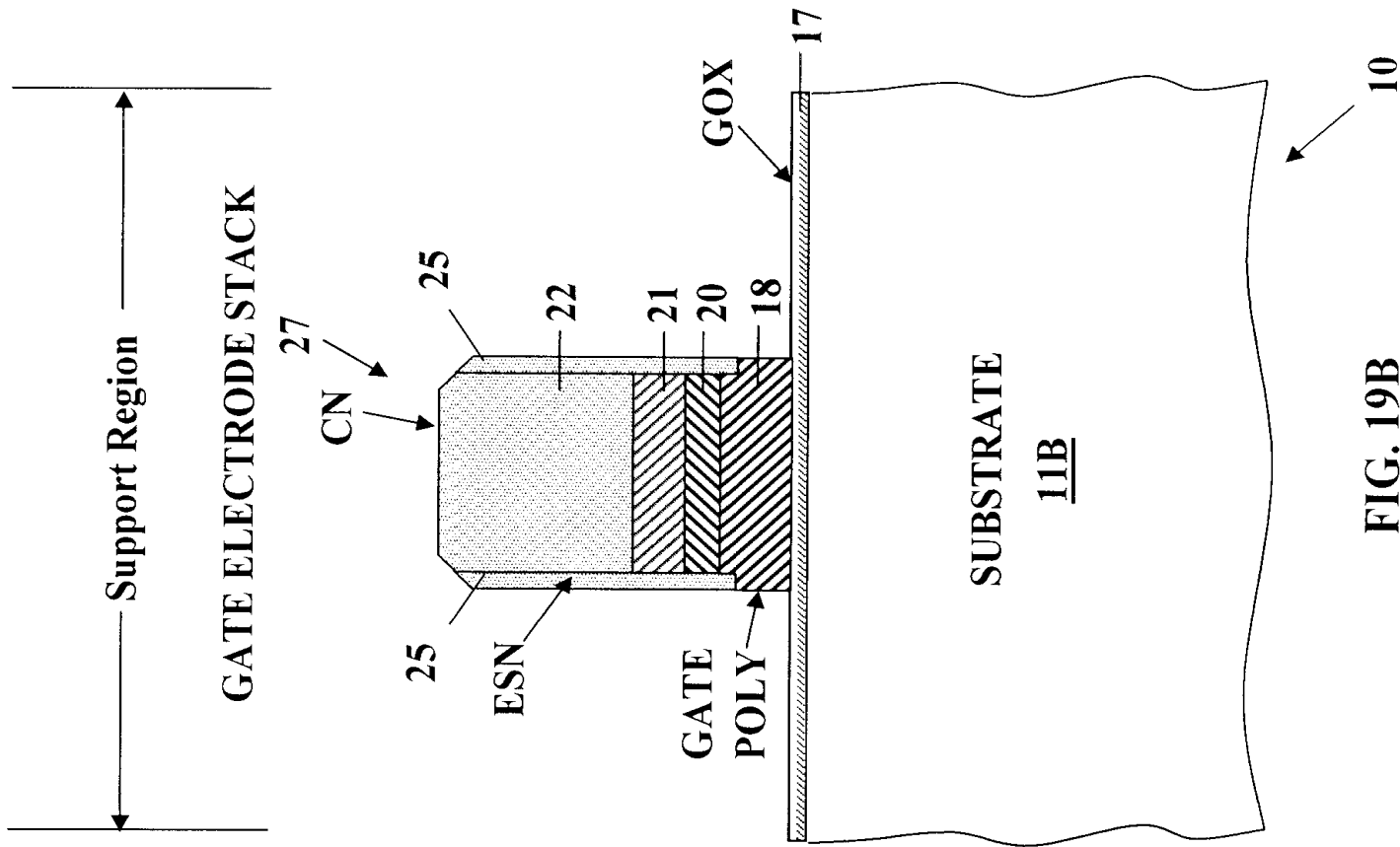
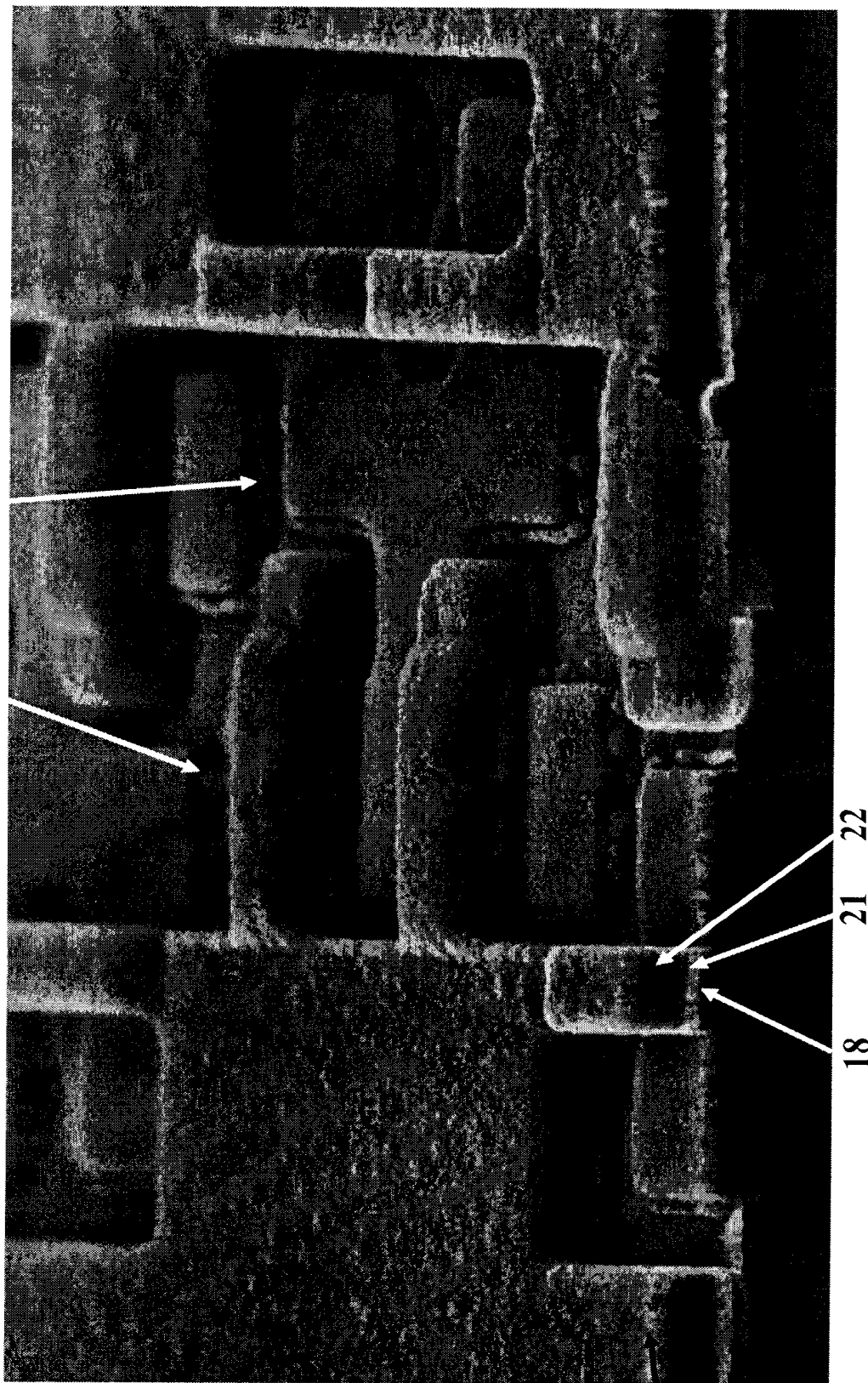


FIG. 19B

POLYSILICON RESIDUE LEFT BY  
INSUFFICIENT POLYSILICON OVERTCH  
DUE TO A SHORTER RIE



Cr for decoration

PRIOR ART

FIG. 20

21/21

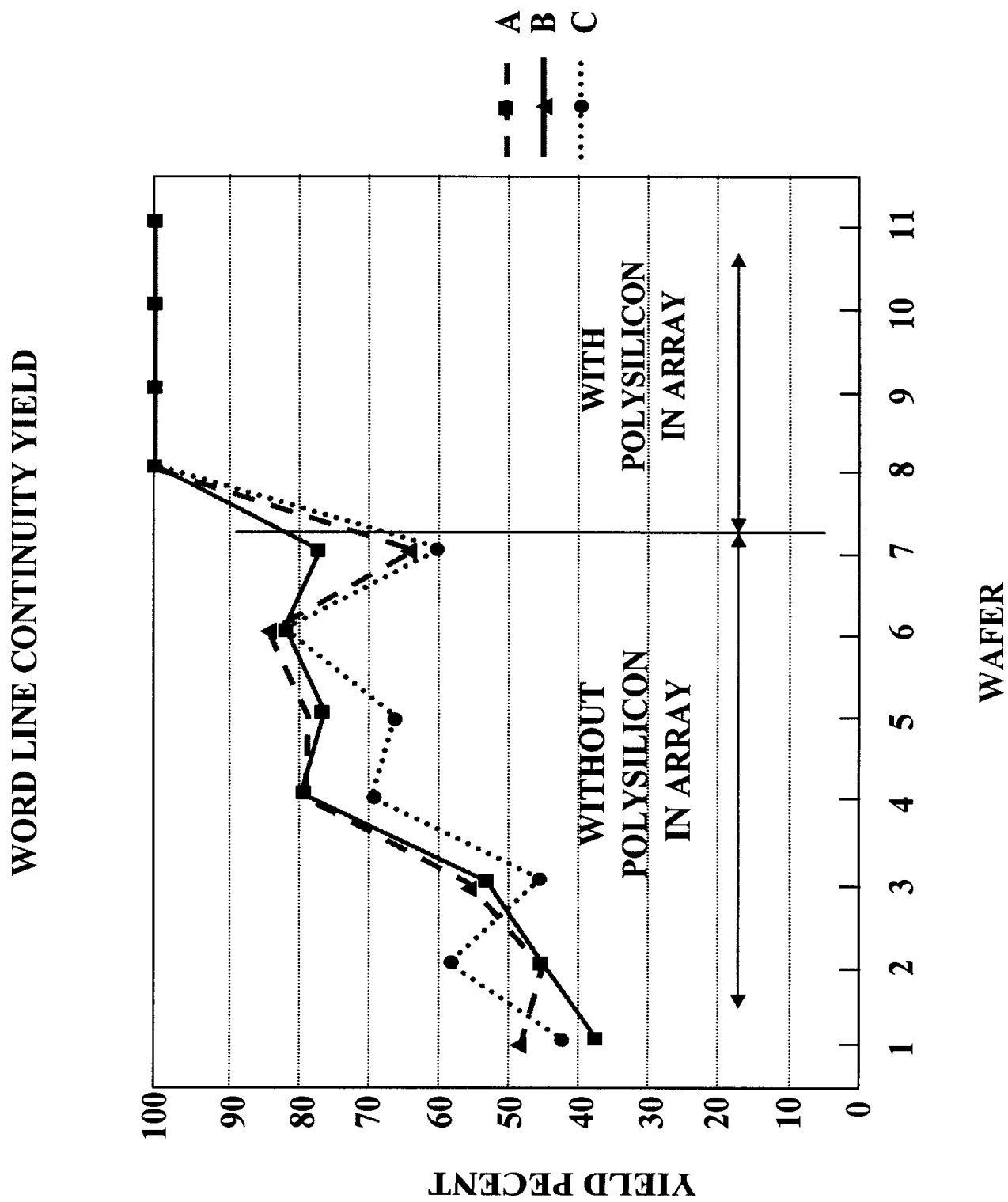


FIG. 21